

**Remarks/Arguments**

Applicants thank Examiner Arbes for his careful examination of this application and for allowing claims 17-20. In response to the Office Action of February 22, 2006, applicants amend this application as follows:

1. The title of this application is changed to -- Wirebonder to Bond an IC Chip to a Substrate.
2. Claims 1-16 are canceled from this examination.

Applicants respectfully submit that as amended, this application is in allowable form.

Respectfully submitted,

/Yingsheng Tung/

Texas Instruments Incorporated  
P. O. Box 655474 MS 3999  
Dallas, TX 75264  
(972) 917-5355  
(972) 917-4418 (fax)

Yingsheng Tung  
Reg. No. 52,305  
Attorney for Applicants